NEXT GENERATION TRANSPORT AIRCRAFT BY Seminar

University of Washington, Tohoku University and Toray Composites (America), Inc.

Please join us on Tuesday, June 17th at 17:00PST for a joint seminar between University of Washington, Tohoku University, and Toray Composites (America)

PROGRAM

17:00-17:15 "Mechanical property evaluation for Epoxy resin by molecular dynamics simulation"

Koichi Tanabe

Department of Aerospace Engineering, Tohoku University



17:15-17:30 "Numerical simulation for thermal curing of polymer resin under electric field"

Shinya Hatori

Department of Mechanical Engineering, Tokyo University of Science







